



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

*: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-04-23
Contact Name *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Authorized Representative *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SMAJ26CA-TR	8HST*TWB030C	A	64BA	2018-04-23
	Amount	UoM	Unit type	ST ECOPACK Grade
	70	mg	Each	ECOPACK2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.14-2.76-1.94	2	J bend	
Comment	SMA			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 15th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	Die	100
Lead	1.00	Soft solder	14243

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	8HST*TWB030C					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	1.112	mg	supplier	die	Silicon (Si)	7440-21-3		1.092	mg	982014	15600
				supplier	metallization	Aluminium (Al)	7429-90-5		0.003	mg	2698	43
				supplier	Passivation	Silicon Oxide	7631-86-9		0.004	mg	3597	57
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.004	mg	3597	57
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1799	29
Leadframe	M-004 Copper and its alloys	29.807	mg	supplier	back side metallization	Nickel (Ni)	7440-02-0		0.007	mg	6295	100
				supplier	alloy	Copper (Cu)	7440-50-8		29.768	mg	998692	425257
				supplier	alloy	Iron (Fe)	7439-89-6		0.030	mg	1006	429
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.009	mg	302	129
Soft solder	Solder	1.083	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	0.997	mg	920591	14243
				supplier	solder	Silver (Ag)	7440-22-4		0.027	mg	24931	386
				supplier	solder	Tin (Sn)	7440-31-5		0.054	mg	49861	771
				supplier	solder	flux residue	Proprietary		0.005	mg	4617	71
Encapsulation	M-011 Other inorganic materials	25.776	mg	supplier	mold compound	Amorphous Silica	7631-86-9		18.843	mg	731029	269186
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		4.898	mg	190022	69971
				supplier	mold compound	Phenol resin	9003-35-4		0.773	mg	29989	11043
				supplier	mold compound	Bisphenol A-bisphenol A diglycidyle ether poly	25036-25-3		0.773	mg	29989	11043
				supplier	mold compound	Carbon black	1333-86-4		0.232	mg	9001	3314
				supplier	mold compound	Triphenylphosphine	603-35-0		0.180	mg	6983	2571
Connections coating	Solder	0.741	mg	supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		0.077	mg	2987	1100
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.741	mg	1000000	10586
Clip		11.481	mg	supplier	alloy	Copper (Cu)	7440-50-8		11.481	mg	1000000	164014